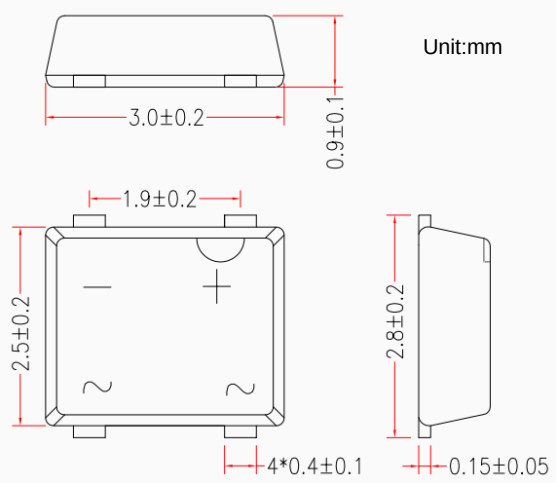
P7

Subminiature Plane Mount Bridge Rectifier

FEATURES

- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- High forward surge capability
- High temperature soldering ：260℃/10 seconds at terminals
- Lead free in comply with EU ROHS 2011/65/EU directives

PMB



Mechanical Data

- **Case** : PMB
- **Terminals** : Solder plated, solderable per MIL-STD-750,Method 2026
- **Polarity** : Cathode line denotes the cathode end
- **Mounting Position** : Any

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating at 25℃ ambient temperature unless otherwise specified.

Single phase, half wave ,60Hz, resistive or inductive load. For capacitive load, derate current by 20%

CHARACTERISTICS	Symbols	P7	UNIT
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS Bridge Input Voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Maximum Average Forward Rectified Current	$I_{(AV)}$	0.2	A
Peak Forward Surage Current 8.3ms Single Half Sine-Wave Super Imposed on Rated Load (JEDEC Method)	I_{FSM}	6	A
Maximum Forward Voltage at 0.2A DC	V_F	1	V
Maximum DC Reverse Current T_A=25℃	I_R	5.0	μA
at Rated DC Blocking Voltage T_A=125℃		500	μA
Typical Junction Capacitance (VR=4.0V, f=1MHZ)	C_J	13	pF
Typical Thermal Resistance	$R_{\theta JA}$	200	℃/W
Operating Temperature Range	T_J	-55 to +150	℃
Storage Temperature Range	T_{STG}	-55 to +150	℃

Characteristic Curves (T_A=25 ℃ unless otherwise noted)

Fig.1 Forward Current Derating Curve

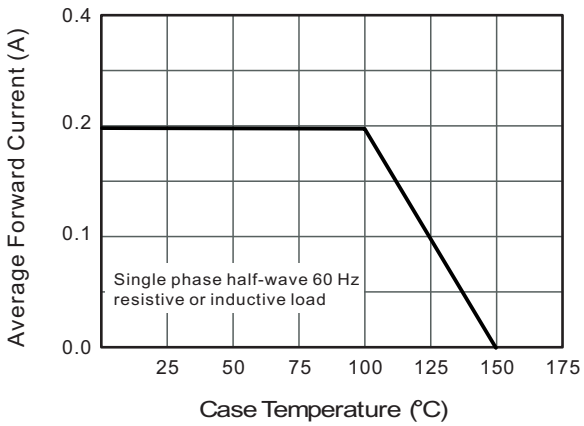


Fig.2 Typical Reverse Characteristics

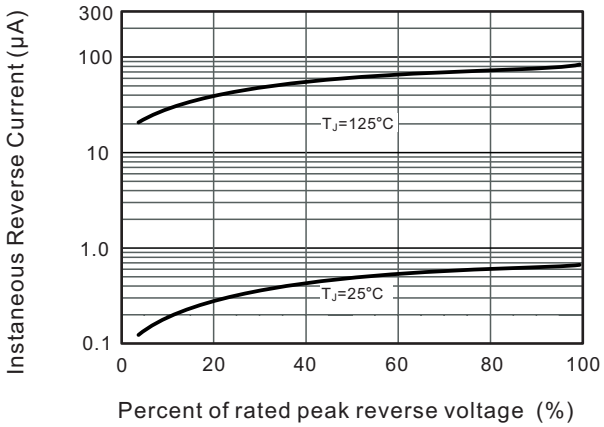


Fig.3 Typical Forward Characteristic

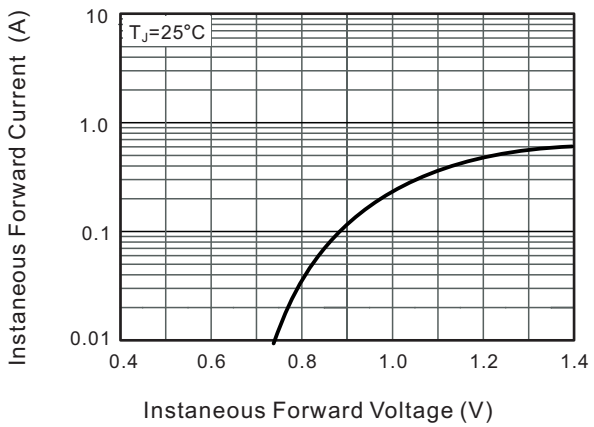
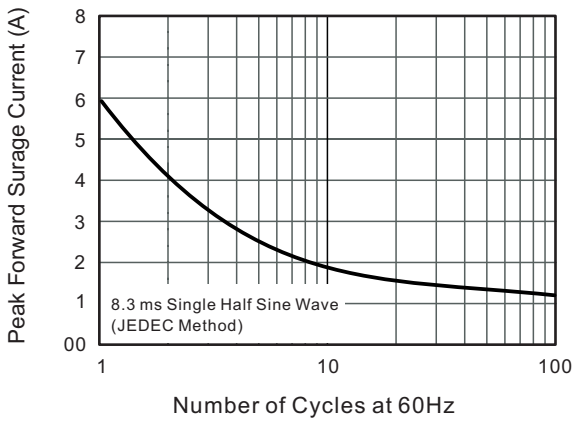


Fig.4 Maximum Non-Repetitive Peak Forward Surage Current



The recommended mounting pad size